

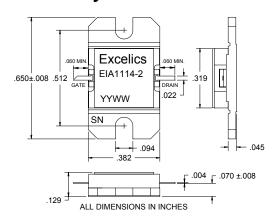
EIA1114-2

UPDATED 07/25/2006

11.0-14.0GHz 2-Watt Internally Matched Power FET

FEATURES

- 11.0-14.0GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +33.5 dBm Output Power at 1dB Compression
- 7.0 dB Power Gain at 1dB Compression
- 25% Power Added Efficiency
- -36 dBc IM3 at Po = 22.5 dBm SCL
- **Hermetic Metal Flange Package**
- 100% Tested for DC, RF, and R_{TH}





ELECTRICAL CHARACTERISTICS (Ta = 25°C)

Caution! ESD sensitive device.

SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression $f = 11.0-14.0 GHz$ $V_{DS} = 8 \text{ V}, I_{DSQ} \approx 750 \text{mA}$	32.5	33.5		dBm
G _{1dB}	Gain at 1dB Compression $f = 11.0-14.0 GHz$ $V_{DS} = 8 \text{ V}, I_{DSQ} \approx 750 \text{mA}$	6.0	7.0		dB
ΔG	Gain Flatness $f = 11.0-14.0 GHz$ $V_{DS} = 8 \text{ V}, I_{DSQ} \approx 750 \text{mA}$			±0.8	dB
PAE	Power Added Efficiency at 1dB Compression V_{DS} = 8 V, $I_{DSQ} \approx 750 \text{mA}$ f = 11.0-14.0GHz		25		%
Id_{1dB}	Drain Current at 1dB Compression f = 11.0-14.0GHz		850	1000	mA
IM3	Output 3rd Order Intermodulation Distortion Δf = 10 MHz 2-Tone Test; Pout = 22.5 dBm S.C.L ² V_{DS} = 8 V, I_{DSQ} ≈ 65% IDSS f = 14.0GHz		-36		dBc
I _{DSS}	Saturated Drain Current V _{DS} = 3 V, V _{GS} = 0 V		1440	1800	mA
V _P	Pinch-off Voltage V _{DS} = 3 V, I _{DS} = 15 mA		-1.0	-2.5	V
R _{TH}	Thermal Resistance ³		11.0	12.0	°C/W

Note: 1) Tested with 100 Ohm gate resistor.

2) S.C.L. = Single Carrier Level.

3) Overall Rth depends on case mounting.

ABSOLUTE MAXIMUM RATING^{1,2}

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²
Vds	Drain-Source Voltage	10	8V
Vgs	Gate-Source Voltage	-5	-3V
lgsf	Forward Gate Current	21.6mA	7.2mA
lgsr	Reverse Gate Current	-3.6mA	-1.2mA
Pin	Input Power	32.5dBm	@ 3dB Compression
w.DataShe dch l.com	Channel Temperature	175°C	175°C
Tstg	Storage Temperature	-65 to +175 °C	-65 to +175 °C
Pt	Total Power Dissipation	12W	12W

Note: 1. Exceeding any of the above ratings may result in permanent damage.

2. Exceeding any of the above ratings may reduce MTTF below design goals.